

Form PTO-1449	Document Number (Specified)	Atticase Number
INFORMATION DISCLOSURE CITATION IN AN APPLICATION	IME-03-005	10/748,736
(Use several sheets if necessary)	Applicant: Wang Ec Hua et al.	
	Filing Date	Group Art Unit
	12/30/03	2813

## U. S. PATENT DOCUMENTS

## FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

**OTHER DOCUMENTS** (Including Author, Title, Date, Portion or Pages, Etc.)

CC - Larry Gilg, Die Products Consortium, Austin, TX - EP4P, 7/1/02,  
 "Wafer-Level vs. Singulated Die Burn-In and Test"

CC - Beth Koser, et al., "Encapsulated Double-Bump WL-CSP: Design and  
 Reliability", Proc. 51st Electronic Component Tech. Conf. 2001, pp.35-39.

CC - JSimone, "Development and Board Level Reliability of a Wafer-  
 level csp", Proc. 41ST IEMT/ IMC 2000, pp. 22-27.

EXAMINER DATE CONSIDERED

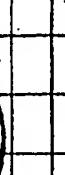
Chandra Chaudhari

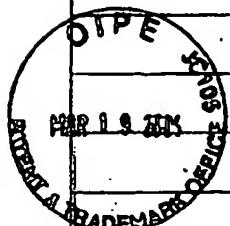
1-05

**EXAMINER:** Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

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## U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	REND DATE IF APPROPRIATE
						



## FOREIGN PATENT DOCUMENTS

**OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)**

CC -	S.I. Desada, et al., "Wafer Level Packaging Technology in Japan", Proc. 4th IEMT / IMC, 2000, pp. 4-9, (Fig. 2).
CC -	Advanced IC packaging markets and trends, pp. 4-49 to 4-51, Electronic Trend Publication, 6 <sup>th</sup> Edition, 2002.
CC -	Bakir, et al., "Sea of Leads Ultra-High-Density Compliant Wafer-Level Packaging Technology", Proc. 52nd Elec. Component Tech. Conf.,

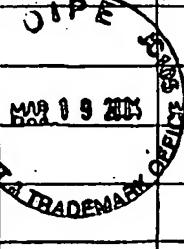
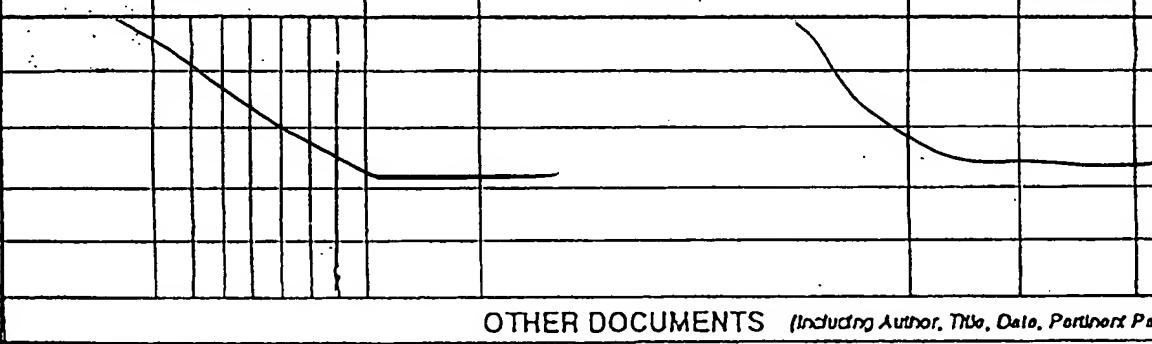
EXXONER 2002, pp. 1087-1094.

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1-05

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	DOCUMENT NUMBER	DATE	COUNTRY		CLASS	SUBCLASS	Translation YES NO
							
OTHER DOCUMENTS (including Author, Title, Date, Page Number, Etc.)							
CC -	<p>P. Garrou, et al., "Cyclotene BCB Resin for Bumping and Water Level Chip Scale Packaging (WL-CSP)", Proc. 3RD</p> <p>ISMT/IMC, pp. 206-211, 1999.</p>						
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